



# SGU | SEMI Global Update

July 2, 2019



**Korea Set to Maintain Equipment Spending Lead**

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**SEMI, Cornell Team to Speed Tech Development**

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**Groundbreaking Survey to Drive Best Practices**

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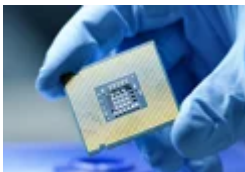
**Intel, TSMC Vow to Focus on 3D IC Packaging**

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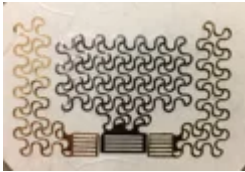
**Best of West Finalists Unveiled**

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**Atoms to Systems in Next-Gen SoC Design**

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## SEMI-Related: E-Tattoo for Cardiac Care

### More News...

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[Smart Manufacturing](#)

[Advanced Packaging](#)

### Upcoming Events

Jul 9-11	<a href="#">SEMICON West 2019</a>	San Francisco, CA
Sep 18-20	<a href="#">SEMICON Taiwan 2019</a>	Taipei, Taiwan
Sep 23-25	<a href="#">Strategic Materials Conference — SMC 2019</a>	San Jose, CA

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